## Errata

# MSP430FG437 Microcontroller



#### **ABSTRACT**

This document describes the known exceptions to the functional specifications (advisories).

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# 1 Functional Advisories

Advisories that affect the device's operation, function, or parametrics.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev E	Rev D	Rev C	Rev B
ADC18	✓	✓	✓	1
ADC25	✓	✓	✓	1
DAC4				1
FLL3	✓	✓	✓	✓
OA1	✓	✓	✓	1
TA12	✓	✓	✓	✓
TA16	✓	✓	✓	1
TA21	✓	✓	✓	1
TAB22	✓	✓	✓	✓
TB2	✓	✓	✓	1
TB16	✓	✓	✓	1
TB24	✓	✓	✓	1
US14				1
US15	✓	✓	✓	✓
WDG2	✓	✓	✓	1
XOSC5	✓			
XOSC9	✓	✓	✓	✓

# 2 Preprogrammed Software Advisories

Advisories that affect factory-programmed software.

✓ The check mark indicates that the issue is present in the specified revision.

The device does not have any errata for this category.

# 3 Debug Only Advisories

Advisories that affect only debug operation.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev E	Rev D	Rev C	Rev B
FFM20	./	./	1	1

## 4 Fixed by Compiler Advisories

Advisories that are resolved by compiler workaround. Refer to each advisory for the IDE and compiler versions with a workaround.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev E	Rev D	Rev C	Rev B
CPU4	1	1	1	1

Refer to the following MSP430 compiler documentation for more details about the CPU bugs workarounds.

TI MSP430 Compiler Tools (Code Composer Studio IDE)



- MSP430 Optimizing C/C++ Compiler: Check the --silicon\_errata option
- MSP430 Assembly Language Tools

## MSP430 GNU Compiler (MSP430-GCC)

- MSP430 GCC Options: Check -msilicon-errata= and -msilicon-errata-warn= options
- MSP430 GCC User's Guide

#### IAR Embedded Workbench

• IAR workarounds for msp430 hardware issues



# 5 Nomenclature, Package Symbolization, and Revision Identification

The revision of the device can be identified by the revision letter on the Package Markings or by the HW\_ID located inside the TLV structure of the device.

#### **5.1 Device Nomenclature**

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP MCU devices. Each MSP MCU commercial family member has one of two prefixes: MSP or XMS. These prefixes represent evolutionary stages of product development from engineering prototypes (XMS) through fully qualified production devices (MSP).

**XMS** – Experimental device that is not necessarily representative of the final device's electrical specifications

MSP - Fully qualified production device

Support tool naming prefixes:

X: Development-support product that has not yet completed Texas Instruments internal qualification testing.

null: Fully-qualified development-support product.

XMS devices and X development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

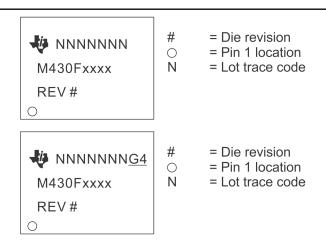
MSP devices have been characterized fully, and the quality and reliability of the device have been demonstrated fully. Tl's standard warranty applies.

Predictions show that prototype devices (XMS) have a greater failure rate than the standard production devices. TI recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the temperature range, package type, and distribution format.

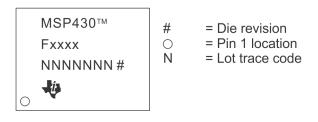
# 5.2 Package Markings

# PN80 LQFP (PN), 80 Pin



ZCA113 NFBGA (ZCA), 113 Pin





## **5.3 Memory-Mapped Hardware Revision (TLV Structure)**

This device does not support reading the hardware revision from memory.

Further guidance on how to locate the TLV structure and read out the HW\_ID can be found in the device User's Guide.

# **6 Advisory Descriptions**

ADC18 ADC Module

Category Functional

Function Incorrect conversion result in extended sample mode

**Description** The ADC12 conversion result can be incorrect if the extended sample mode is selected (SHP = 0), the conversion clock is not the internal ADC12 oscillator (ADC12SSEL > 0),

and one of the following two conditions is true:

- The extended sample input signal SHI is asynchronous to the clock source used for ADC12CLK and the undivided ADC12 input clock frequency exceeds 3.15 MHz.

- The extended sample input signal SHI is synchronous to the clock source used for ADC12CLK and the undivided ADC12 input clock frequency exceeds 6.3 MHz.

Workaround

- Use the pulse sample mode (SHP = 1).

or

- Use the ADC12 internal oscillator as the ADC12 clock source.

or

- Limit the undivided ADC12 input clock frequency to 3.15 MHz.

Ol

- Use the same clock source (such as ACLK or SMCLK) to derive both SHI and ADC12CLK, to achieve synchronous operation, and also limit the undivided ADC12 input clock frequency to 6.3 MHz.

ADC25 ADC Module

**Category** Functional

Function Write to ADC12CTL0 triggers ADC12 when CONSEQ = 00

**Description** If ADC conversions are triggered by the Timer\_B module and the ADC12 is in single-

channel single-conversion mode (CONSEQ = 00), ADC sampling is enabled by write access to any bit(s) in the ADC12CTL0 register. This is contrary to the expected behavior that only the ADC12 enable conversion bit (ADC12ENC) triggers a new ADC12 sample.

Workaround When operating the ADC12 in CONSEQ=00 and a Timer B output is selected as the

sample and hold source, temporarily clear the ADC12ENC bit before writing to other bits in the ADC12CTL0 register. The following capture trigger can then be re-enabled by

setting ADC12ENC = 1.

CPU4 CPU Module

Category Compiler-Fixed

Function PUSH #4, PUSH #8

**Description** The single operand instruction PUSH cannot use the internal constants (CG) 4 and 8. The

other internal constants (0, 1, 2, -1) can be used. The number of clock cycles is different:

PUSH #CG uses address mode 00, requiring 3 cycles, 1 word instruction PUSH #4/#8 uses address mode 11, requiring 5 cycles, 2 word instruction

**Workaround** Refer to the table below for compiler-specific fix implementation information.



www.ti.com Advisory Descriptions

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	IAR EW430 v2.x until v6.20	User is required to add the compiler flag option below hw_workaround=CPU4
IAR Embedded Workbench	IAR EW430 v6.20 or later	Workaround is automatically enabled
TI MSP430 Compiler Tools (Code Composer Studio)	v1.1 or later	
MSP430 GNU Compiler (MSP430-GCC)	MSP430-GCC 4.9 build 167 or later	

DAC4 DAC Module

Category Functional

**Function** DAC1 overwrites an input of the SVS comparator

**Description** DAC1, when enabled (DAC12\_1CTL.DAC12AMPx >0), overrides the input of the SVS

comparator if SVSCTL.VLDx = 1111 (comparing external input voltage SVSIN to 1.25 V.) This is caused by a conflict between SVS and DAC1 at Port 6.7. This behavior only

affects DAC output pins shared with SVSIN function.

**Workaround** 1) Do not enable DAC1 when SVS is used with VLDx = 1111

OR

2) Use DAC output pin not shared with SVSIN function

EEM20 EEM Module

Category Debug

**Function** Debugger might clear interrupt flags

**Description** During debugging read-sensitive interrupt flags might be cleared as soon as the debugger

stops. This is valid in both single-stepping and free run modes.

Workaround None.

FLL3 FLL Module

**Category** Functional

**FLLDx** = 11 for /8 may generate an unstable MCLK frequency

**Description** When setting the FLL to higher frequencies using FLLDx = 11 (/8) the output frequency

of the FLL may have a larger frequency variation (e.g. averaged over 2sec) as well as a lower average output frequency than expected when compared to the other FLLDx bit

settings.

Workaround None

OA1 OA Module

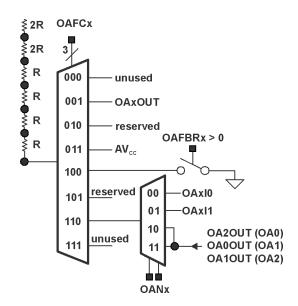
**Category** Functional

**Function** 

OAxI1 input selection

#### **Description**

Referring to the OA block diagram in the MSP430x4xx User's Guide, the internal connection of the OAxI1 input to the OAFCx mux is incorrect. The signal input to the OAFCx mux when OANx = 01 is OA0I1 for all OAs. See the figure below for a graphical representation.



Workaround

None

TA12

TA Module

Category

**Functional** 

**Function** 

Interrupt is lost (slow ACLK)

**Description** 

Timer\_A counter is running with slow clock (external TACLK or ACLK)compared to MCLK. The compare mode is selected for the capture/compare channel and the CCRx register is incremented by one with the occurring compare interrupt (if TAR = CCRx). Due to the fast MCLK the CCRx register increment (CCRx = CCRx+1) happens before the Timer\_A counter has incremented again. Therefore the next compare interrupt should happen at once with the next Timer\_A counter increment (if TAR = CCRx + 1). This interrupt gets lost.

Workaround

Switch capture/compare mode to capture mode before the CCRx register increment. Switch back to compare mode afterwards.

**TA16** 

TA Module

Category

**Functional** 

**Function** 

First increment of TAR erroneous when IDx > 00

**Description** 

The first increment of TAR after any timer clear event (POR/TACLR) happens immediately following the first positive edge of the selected clock source (INCLK, SMCLK, ACLK or TACLK). This is independent of the clock input divider settings (ID0, ID1). All following TAR increments are performed correctly with the selected IDx settings.

Workaround

None

www.ti.com Advisory Descriptions

TA21 TA Module

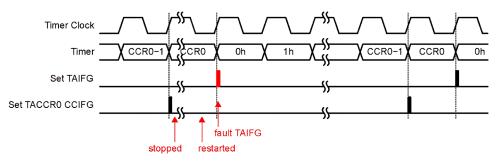
**Category** Functional

**Function** TAIFG Flag is erroneously set after Timer A restarts in Up Mode

**Description** In Up Mode, the TAIFG flag should only be set when the timer counts from TACCR0 to zero. However, if the Timer A is stopped at TAR = TACCR0, then cleared (TAR=0) by

setting the TACLR bit, and finally restarted in Up Mode, the next rising edge of the TACLK

will erroneously set the TAIFG flag.



Workaround None.

TAB22 TAB Module

**Category** Functional

Function Timer\_A/Timer\_B register modification after Watchdog Timer PUC

**Description** Unwanted modification of the Timer\_A/Timer\_B registers TACTL/TBCTL and TAIV/TBIV

can occur when a PUC is generated by the Watchdog Timer(WDT) in Watchdog mode and any Timer\_A/Timer\_B counter register TACCRx/TBCCRx is incremented/

decremented (Timer\_A/Timer\_B does not need to be running).

Workaround Initialize TACTL/TBCTL register after the reset occurs using a MOV instruction (BIS/BIC

may not fully initialize the register). TAIV/TBIV is automatically cleared following this

initialization.

Example code:

MOV.W #VAL, &TACTL

or

MOV.W #VAL, &TBCTL

Where, VAL=0, if Timer is not used in application otherwise, user defined per desired

function.

TB2 TB Module

**Category** Functional

Function Interrupt is lost (slow ACLK)

**Description** Timer B counter is running with slow clock (external TBCLK or ACLK) compared to

MCLK. The compare mode is selected for the capture/compare channel and the CCRx register is incremented by 1 with the occurring compare interrupt (if TBR = CCRx). Due to the fast MCLK, the CCRx register increment (CCRx = CCRx + 1) happens before the Timer B counter has incremented again. Therefore, the next compare interrupt should



happen at once with the next Timer\_B counter increment (if TBR = CCRx + 1). This

interrupt is lost.

**Workaround** Switch capture/compare mode to capture mode before the CCRx register increment.

Switch back to compare mode afterward.

TB16 TB Module

**Category** Functional

**Function** First increment of TBR erroneous when IDx > 00

**Description** The first increment of TBR after any timer clear event (POR/TBCLR) happens

immediately following the first positive edge of the selected clock source (INCLK, SMCLK, ACLK, or TBCLK). This is independent of the clock input divider settings (ID0, ID1). All following TBR increments are performed correctly with the selected IDx settings.

Workaround None

TB24 TB Module

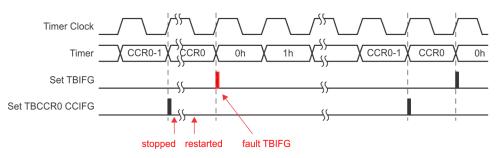
**Category** Functional

Function TBIFG Flag is erroneously set after Timer B restarts in Up Mode

**Description** In Up Mode, the TBIFG flag should only be set when the timer resets from TBCCR0 to

zero. However, if the Timer B is stopped at TBR = TBCCR0, then cleared (TBR=0) by setting the TBCLR bit, and finally restarted in Up Mode, the next rising edge of the TBCLK

will erroneously set the TBIFG flag.



Workaround None.

US14 USART Module

**Category** Functional

**Function** Start edge of received characters may be ignored

**Description** When using the USART in UART mode with UxBR0 = 0x03 and UxBR1 = 0x00, the start

edge of received characters may be ignored due to internal timing conflicts within the

UART state machine. This condition does not apply when UxBR0 is > 0x03.

Workaround None

US15 USART Module

Category Functional



www.ti.com Advisory Descriptions

**Function** UART receive with two stop bits

**Description** USART hardware does not detect a missing second stop bit when SPB = 1.

The Framing Error Flag (FE) will not be set under this condition and erroneous data

reception may occur.

**Workaround** None (Configure USART for a single stop bit, SPB = 0)

WDG2 WDG Module

**Category** Functional

Function Incorrectly accessing a flash control register

**Description** If a key violation is caused by incorrectly accessing a flash control register, the watchdog

interrupt flag is set in addition to the expected PUC.

Workaround None

XOSC5 XOSC Module

Category Functional

**Function** LF crystal failures may not be properly detected by the oscillator fault circuitry

**Description** The oscillator fault error detection of the LFXT1 oscillator in low frequency mode (XTS =

0) may not work reliably causing a failing crystal to go undetected by the CPU, i.e. OFIFG

will not be set.

Workaround None

XOSC9 XOSC Module

**Category** Functional

**Function** XT1 Oscillator may not function as expected in HF mode

**Description** XT1 oscillator does not work correctly in high frequency mode at supply voltages below

2.0V with crystal frequency > 4MHz.

**Workaround** None. When XT1 oscillator is used in HF mode with crystal frequency > 4MHz ensure a

supply voltage > 2.2V.

Revision History www.ti.com

#### 7 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

# Changes from May 12, 2021 to May 17, 2021

Page

Changed the document format and structure; updated the numbering format for tables, figures, and cross 

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